

JUN 06 2002

TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
E0520CIP

In Re Application Of: **Kashmir S. Sahota, Diana M. Schonauer, Johannes F. Groschopf, Gerd F.C. Marxsen, Steven A. Avanzino**

Serial No.
09/749,191

Filing Date
December 26, 2000

Examiner
L. Umez-Eronini

Group Art Unit
1765

Title: **"PREVENTION OF PRECIPITATION DEFECTS ON COPPER INTERCONNECTS DURING CMP BY USE SOLUTIONS CONTAINING ORGANIC COMPOUNDS WITH SILICA ADSORPTION AND COPPER CORROSION INHIBITING PROPERTIES"**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

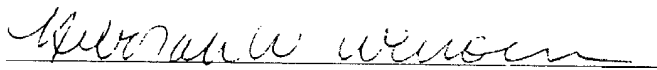
Amendment Transmittal Letter (in duplicate)
Amendment and Response to Office Action (11 pp)
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in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **01-0365** as described below. A duplicate copy of this sheet is enclosed.
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Dated: May 26, 2002

Deborah W. Wenocur, Reg. No. 40,221
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I certify that this document and fee is being deposited on May 28, 2002 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

CC:

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): K. Sahota, D. Schonauer, J. Groschopf, G. Marxsen, and S. Avanzino

Docket No.

E0520CIP

Serial No.
09/749,191

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December 26, 2000

Examiner
L. Umez Eronini

Group Art Unit
1765

Invention: Prevention of Precipitation Defects on Copper Interconnects During CMP by Use of Solutions Containing Organic Compounds with Silica Adsorption and Copper Corrosion Inhibiting Properties

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	71 -	73 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	5 -	5 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

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 - ☒ Any patent application processing fees under 37 CFR 1.17.

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Dated: May 26 2002

Signature

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